

### **AMENDMENTS TO THE SPECIFICATION**

Please amend the specification as follows.

Please replace paragraph [0018] of the specification as originally filed with the paragraph below, which is marked-up to show the changes therein:

[0018] According to an embodiment of the present invention, a method for inspecting a substrate includes loading a substrate on a first stage, acquiring a first image of a peripheral portion of the substrate loaded on the first stage, inspecting results of an edge bead removal process and an edge exposure of ~~water~~ wafer process performed on the substrate using the first image, transferring the substrate onto a second stage, acquiring a second image of another portion of the substrate supported by the second stage, and inspecting defects of patterns formed on the substrate using the second image.

Please replace paragraph [0020] of the specification as originally filed with the paragraph below, which is marked-up to show the changes therein:

[0020] Preferably, inspecting the results of the edge bead removal process and the edge exposure of ~~water~~ wafer process further includes calculating a distance from a side surface of the substrate to a side surface of a photoresist film using the first image, and judging the results of the edge bead removal process and the edge exposure of ~~water~~ wafer process using the calculated distance.